

**AMENDMENTS TO THE SPECIFICATION**

Please amend the paragraph beginning on page 9, line 36 as follows:

With the second variant according to Fig. 6b there is provided an additional cooling body 25 as heat transport means, which is so shaped that a heat exchange surface between power triac 22a and heat exchanger element 23 which is as great as possible is formed. The cooling body 25 23 is placed between the base circuit board 14 24 on the one hand and the power triac 22a and the heat exchanger element 23 on the other hand and makes possible, in comparison to the variant illustrated in Fig. 6a, improved heat conduction.